



Navitas Semiconductor to Report Q3 2026 Financial Results on Tuesday, November 3, 2026

October 13, 2026

TORRANCE, Calif., Oct. 13, 2026 (GLOBE NEWSWIRE) -- [Navitas Semiconductor](#) (Nasdaq: NVTs) today announced that it will report third quarter 2026 financial results on Tuesday, November 3, 2026, after the market close.

Navitas' President and CEO, Chris Alexandre, and CFO, Tonya Stevens, will host a conference call at 2:00 p.m. Pacific Time to discuss the Company's financial results and business outlook.

Analysts and investors are invited to join the conference call using the following information:

When: **Tuesday, November 3, 2026**

Time: **2:00 p.m. Pacific Time** (5:00 p.m. Eastern Time)

Toll Free Dial-in: **1-800-715-9871** or **646-307-1963**

Conference ID: **5069224**

Webcast and Slides: [Click Here](#)

Additionally, a live and archived audio webcast of the conference call as well as supporting presentation materials will be accessible from the Investor Relations section of the Company's website at ir.navitassemi.com.

About Navitas

[Navitas Semiconductor](#) (Nasdaq: NVTs) is a leader in next-generation power semiconductors and power delivery solutions, pioneering GaN, high-voltage and ultra-high-voltage SiC, and IVR technologies for AI infrastructure, including data centers and energy and grid systems, as well as additional markets such as high-performance computing and industrial electrification. Collectively, these technologies address the complete grid-to-xPU power architecture, breaking the AI infrastructure power wall and enabling higher efficiency, greater power density, and increased performance across the entire power chain. Navitas' [GaNFast™](#) FETs deliver industry-leading power density, efficiency, and high-speed performance, while GaNFast™ power ICs integrate GaN power, drive, control, sensing, and protection to enable faster, more efficient power conversion, leading to smaller and more reliable systems. The [GeneSiC™](#) portfolio combines proprietary trench-assisted planar (TAP) SiC technology with leading-edge discrete packaging and SiCPAK™ power modules to deliver industry-leading efficiency, ruggedness and performance. [Claros™](#) IVR technologies extend power delivery directly to the xPU, enabling customers to implement vertical power delivery (VPD) and embedded power delivery (EPD) architectures with high-density power conversion beneath or within millimeters of the processor, minimizing power-delivery losses and impedance while enabling ultra-fast transient response, higher efficiency and maximum power density. Navitas has over 450 patents issued or pending and is a leader in 800 VDC and the advanced AI power infrastructure ecosystem.

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